

PRODUCT/PROCESS CHANGE NOTICE (PCN)

<p>PCN Number: 04-11</p> <p>Date Issued: June 18, 2004</p> <p>Product(s) Affected: PI5C3384C</p> <p>Manufacturing Location Affected: Hynix Semiconductor</p> <p>Date Effective: September 18, 2004 – standard 90 day waiting period (some customers may require longer timeframes)</p>	<p>Means of Distinguishing Changed Devices:</p> <p><input type="checkbox"/> Product Mark:</p> <p><input type="checkbox"/> Back Mark</p> <p><input checked="" type="checkbox"/> Date Code: Wafer Fab ID letter code *</p> <p><input type="checkbox"/> Other</p> <p><i>* G - last letter of date code signifies Hynix</i></p>
<p>Contact: Ed Mello</p> <p>Title: Director, Quality Systems</p> <p>Phone: (408) 435-0800, Ext. 207</p> <p>Fax: (408) 321-0324</p> <p>eMail: emello@pericom.com</p>	<p>Attachment: <input checked="" type="checkbox"/> Yes; <input type="checkbox"/> No</p> <p>Samples: Available when requested from Pericom Sales.</p>
<p>Description and Purpose of Change:</p> <p>To increase Pericom's manufacturing capacity for this product, we've added this device type to Hynix's standard 0.5-micron (HS0F5F) process that was approved by Pericom over 5 years ago. Generic Information on Hynix's basic process is at:</p> <p>http://www.hynix.com/eng/products/system_ic/sms/down/procs_5um_5VSTD.pdf</p> <p>Hynix Semiconductor's facilities are certified to ISO-9000-2000 & ISO-14001, and are located in Gumi, Korea. Their website is at:</p> <p>http://www.hynix.com/eng/index.html</p>	<p><input type="checkbox"/> Die Technology</p> <p><input checked="" type="checkbox"/> Wafer Fabrication</p> <p><input type="checkbox"/> Assembly Process</p> <p><input type="checkbox"/> Equipment</p> <p><input type="checkbox"/> Material</p> <p><input type="checkbox"/> Testing</p> <p><input checked="" type="checkbox"/> Manufacturing Site</p> <p><input type="checkbox"/> Data Sheet</p> <p><input type="checkbox"/> Other:</p>
<p>Reliability/Qualification Summary: Copy of Electrical Characterization report is attached.</p>	
<p>Customer Acknowledgement of Receipt:</p> <hr style="border-top: 1px dashed black;"/> <p>Customer: _____</p> <p>Name: _____</p> <p>Title: _____</p> <p>Date: _____</p> <p>E-Mail: _____</p> <p>Phone: _____</p> <p>Fax: _____</p> <p><input type="checkbox"/> Approval for shipments prior to PCN effective date</p> <p>Customer Comments (Optional): _____</p>	

Date: November 5, 2003

Subject: PI5C3384C Characterization Comparison Report

Introduction:

The PI5C3384C product was characterized comparing the new Hynix version with the CSMS wafer fab version. Ron and AC measurements were done side by side for a direct comparison

Reference:

Hynix Process: 0.5 μ m, 1P2M, 5V Process – 8-inch wafer

Die Array: P5CH

Die size: 23 x 60 mils

Date Code: Z03430G

Lot #: ENYD02

Package: QSOP (Q24)

CSMS Process: 0.6 μ m, 1P2M, 5V Process – 6-inch wafer

Die Array: BS24

Die size: 34.6 x 64 mils

Date Code: Y0302CZC

Lot #: 208190

Package: QSOP (Q24)

Equipment:

HP power supply & DMM

HP4145B DC Analyzer

HP4285A LCR Meter

TDS8000 Oscilloscope

HP8110A Pulse Generator

HP8116A Pulse Generator

Thermostream TP041000-A

Tables:

Tables 1-2: DC Characteristics - Tester

Table 3: DC Characteristics - Bench

Table 4: Ron Measurements, all paths, Vcc=4.75V, 25°C - Bench

Table 5: Capacitance at 25C - Bench

Table 6: AC Characteristics - Bench

Table 7: Dynamic ICC, Vcc=5.25V, 25°C - Bench

Table 8: Undershoot Protection Test, Vcc=5V - Bench

Conclusion:

1. Ron of Hynix version is 0.5 Ω lower on average at 25°C, than that of CSMS at Ion = 48mA, and 0.1 Ω lower at Ion = 15mA.
2. The speed of Hynix version is somewhat faster than that of CSMS
3. The Hynix product meets all datasheet spec requirements, and is equivalent to the CSMS product.

Table 1. DC Characteristics, 25 Units, 25C –TESTER DATA

Param.	Test Conditions	Vcc	Hynix				Specification		
			Min	Avg	max	Std Dev	Min	Max	Units
VIH	Input High Volt.	4.75V	1.21	1.22	1.26	0.017	2.00		V
VIL	Input Low Volt.	4.75 V	1.18	1.18	1.18	0.0		0.80	V
IIL	Vin= 0 V	5.25 V	-95.7	-12.4	65.32	39.8	-1u	1 u	nA
IIH	Vin= 5.25 V	5.25 V	-64.45	40.76	112.26	49.59		1 u	nA
IOZL	Vout= 0 V	5.25 V	-81.55	-26.5	17.24	22.86		1 u	nA
IOZH	Vout= 5.25V	5.25 V	-45.46	14.27	90.96	36.84		1 u	nA
VIK	Iin=-18mA,	4.75 V	-1.21	-1.1	-1.06	0.002		-1.2	V
	A pin or /BE	4.75V	-1.79	-1.75	-1.72	0.003			
ICC	Vin=0V	5.25 V	42.44	45.34	47.31	1.08	-1	100	μA
ΔICC	Vin=3.4V	5.25 V	0.467	0.510	0.547	0.0182		2.5	mA
Ron	Vin=0.0V, Ion =48mA	4.75V	5.4	5.81	6.25	0.009	5	7	Ohm
Ron	Vin=2.4V, Ion =-15mA	4.75V	8	8.6	8.93	0.003	10	15	Ohm

Table 2. DC Characteristics, 25 Units, 25C –TESTER DATA

Param.	Test Conditions	Vcc	CSMS				Specification		
			Min	Avg	max	Std Dev	Min	Max	Units
VIH	Input High Volt.	4.75V	1.19	1.20	1.23	0.018	2.00		V
VIL	Input Low Volt.	4.75 V	1.18	1.18	1.18	0.0		0.80	V
IIL	Vin= 0 V	5.25 V	-64.45	-7.5	49.67	29.97	-1u	1 u	nA
IIH	Vin= 5.25 V	5.25 V	-64.45	28.99	143.55	56.15		1 u	nA
IOZL	Vout= 0 V	5.25 V	-27.57	-65.87	12.54	20.05		1 u	nA
IOZH	Vout= 5.25V	5.25 V	-45.46	18.16	90.96	38.77		1 u	nA
VIK	Iin=-18mA,	4.75 V	-1.17	-1.12	-1.08	0.023		-1.2	V
	A pin or /BE	4.75V	-1.65	-1.62	1.61	0.017			
ICC	Vin=0V	5.25 V	48.58	52.73	55.84	1.95	-1	100	μA
ΔICC	Vin=3.4V	5.25 V	0.23	0.24	0.26	0.008		2.5	mA
Ron	Vin=0.0V, Ion =48mA	4.75V	6.4	6.7	7.43	0.012	5	7	Ω
Ron	Vin=2.4V, Ion =-15mA	4.75V	10	10.6	11.33	0.006	10	15	Ω

Table 3. DC Characteristics -BENCH DATA

Parameters	Test Conditions	Vcc	Hynix			Specification		
			-10°C	25°C	90°C	Min	Max	Units
V _{IH}	Input High Voltage	4.75V	1.42	1.40	1.38	2.0		V
V _{IH}	Input High Voltage	5.00V	1.45	1.44	1.41	2.0		V
V _{IH}	Input High Voltage	5.25V	1.48	1.47	1.44	2.0		V
V _{IL}	Input Low Voltage	4.75V	1.54	1.53	1.50		0.8	V
V _{IL}	Input Low Voltage	5.00V	1.58	1.57	1.54		0.8	V
V _{IL}	Input Low Voltage	5.25V	1.61	1.59	1.56		0.8	V
V _H	Input Hysteresis	4.75V	0.12	0.13	0.12	typ	0.15	V
V _H	Input Hysteresis	5.00V	0.13	0.13	0.13	typ	0.15	V
V _H	Input Hysteresis	5.25V	0.13	0.12	0.12	typ	0.15	V
I _{IL}	V _{in} = 0V	5.25V	-153p	-61.5p	74.5p		-1u	A
I _{IH}	V _{in} = 5.25V	5.25V	98.3p	143p	186p		1u	A
I _{OZL}	V _{out} = 0V	5.25V	207p	66.2p	341p		-1u	A
I _{OZH}	V _{out} = 5.25V	5.25V	-178p	206p	302p		1u	A
I _{CCL}	V _{in} = 0V	5.25V	50.81	45.80	36.71		100	μA
I _{CCH}	V _{in} = 5.25V	5.25V	50.86	45.93	36.67		100	μA
ΔI _{CC}	V _{in} = 3.4V	5.25V	0.53	0.51	0.50		2.5	mA
R _{on}	I _{on} = 48mA, V _{in} = 0V	4.75V	3.67	4.56	4.96		7	Ω
R _{on}	I _{on} = 15mA, V _{in} = 2.4V	4.75V	6.53	7.86	9.20		15	Ω

Table 4: Ron Measurement, all paths, Vcc=4.75V, 25C -BENCH DATA

Channel	Hynix		CSMS		Units
	I _{on} =48mA V _{in} =0V	I _{on} =15mA V _{in} =2.4V	I _{on} =48mA V _{in} =0V	I _{on} =15mA V _{in} =2.4V	
A0-B0	4.29	7.53	4.90	7.60	Ω
A1-B1	4.10	7.40	4.75	7.47	Ω
A2-B2	4.33	7.60	4.75	7.40	Ω
A3-B3	4.23	7.53	4.75	7.33	Ω
A4-B4	4.29	7.40	4.73	7.47	Ω
A5-B5	4.02	7.20	4.77	7.40	Ω
A6-B6	4.56	7.86	4.71	7.33	Ω
A7-B7	4.08	7.33	4.73	7.26	Ω
A8-B8	4.21	7.40	4.79	7.40	Ω
A9-B9	4.40	7.47	4.87	7.60	Ω

Table 5. Capacitance at 25C -BENCH DATA

Symbol	Description	Vcc	Hynix	CSMS	Typ	Units
C _{in}	Control Input	5 V	3.5	3.3	6	pF
C _{off}	A Cap, Switch Off	5 V	4.1	3.8	6	pF
C _{off}	B Cap, Switch Off	5 V	4.1	4.0	6	pF
C _{on}	A-B, Switch On	5 V	6.7	8.4	8	pF

HP4285A LCR Meter

Table 6. AC Characteristics –BENCH DATA

Symbol	Vcc	Load	Hynix			CSMS			Max Spec	Units
			-10°C	25°C	90°C	-10°C	25°C	90°C		
TpZH	4.75 V	Load A	2.24	2.30	2.45	3.02	3.17	3.47	6.5	ns
TpHZ	4.75 V	Load A	2.90	2.91	2.91	3.43	3.49	3.60	5.5	ns
TpZL	4.75 V	Load B	2.41	2.50	2.68	3.20	3.38	3.39	6.5	ns
TpLZ	4.75 V	Load B	2.39	2.48	2.83	3.12	3.23	3.71	5.5	ns

Load A: 50pF//500Ω

Load B: 50pF//500Ω, 500Ω to 2Vcc

Table 7. Dynamic Icc, Vcc=5.25V, 25C –BENCH DATA

Frequency	Hynix	CSMS	Units
0 MHz	0.0472	0.0558	mA
1MHz	0.110	0.130	mA
5MHz	0.362	0.430	mA
10MHz	0.685	0.804	mA
20MHz	1.292	1.551	mA

Undershoot Protection Test Procedure

1. Switch is disabled with /BE=Vcc.
2. Pin B has a 10kΩ pull-up to Vcc.
3. HP8116A Pulse Generator provides undershoot signal to pin A. Undershoot signal is from 3V to -0.8, -0.9, -1.0 or -1.1V with pulse width 10, 15, 20 or 25ns.
4. TDS8000 Oscilloscope with active probe is used to monitor and measure induced glitch at pin B.
5. HP8116A Pulse Generator is programmed with a narrow undershoot pulse of 25ns but actual pulse width at the narrow end is about 18ns.

Table 8: Undershoot Protection Test, Vcc=5V –BENCH DATA

Negative Signal	Pulse Width	Hynix		CSMS	
		Min (Dip)	VOH (Flat Line)	Min (Dip)	VOH (Flat Line)
-0.8V	10ns	3.00V	3.29V	2.96V	3.30V
-0.8V	15ns	2.86V	3.29V	2.95V	3.30V
-0.8V	20ns	2.84V	3.29V	2.95V	3.30V
-0.8V	25ns	2.84V	3.29V	2.95V	3.30V
-0.9V	10ns	2.99V	3.29V	2.95V	3.29V
-0.9V	15ns	2.34V	3.29V	2.75V	3.29V
-0.9V	20ns	2.22V	3.29V	2.69V	3.29V
-0.9V	25ns	2.23V	3.29V	2.73V	3.29V
-1.0V	10ns	2.99V	3.29V	2.94V	3.29V
-1.0V	15ns	1.54V	3.29V	2.26V	3.29V
-1.0V	20ns	1.25V	3.29V	2.03V	3.29V
-1.0V	25ns	1.29V	3.29V	2.04V	3.29V
-1.1V	10ns	2.87V	3.29V	2.92V	3.30V
-1.1V	15ns	0.59V	3.27V	1.59V	3.29V
-1.1V	20ns	0.11V	3.27V	1.07V	3.29V
-1.1V	25ns	0.14V	3.27V	0.94V	3.29V